# MOSFET - SiC Power, Single N-Channel, TO247-3L

650 V, 12 mΩ, 163 A

# NTHL015N065SC1

## Features

- Typ.  $R_{DS(on)} = 12 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$ Typ.  $R_{DS(on)} = 15 \text{ m}\Omega @ V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge ( $Q_{G(tot)} = 283 \text{ nC}$ )
- High Speed Switching with Low Capacitance (Coss = 430 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

## **Typical Applications**

- SMPS (Switching Mode Power Supplies)
- Solar Inverters
- UPS (Uninterruptable Power Supplies)
- Energy Storage

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Param	Symbol	Value	Unit		
Drain-to-Source Voltage			V <sub>DSS</sub>	650	V
Gate-to-Source Voltage			V <sub>GS</sub>	-8/+22	V
Recommended Operatio of Gate-to-Source Volta		T <sub>C</sub> < 175°C	V <sub>GSop</sub>	-5/+18	V
Continuous Drain Current (Note 1)	Steady State	$T_C = 25^{\circ}C$	۱ <sub>D</sub>	163	A
Power Dissipation (Note 1)			P <sub>D</sub>	643	W
Continuous Drain Current (Note 1)	Steady State	T <sub>C</sub> = 100°C	۱ <sub>D</sub>	115	A
Power Dissipation (Note 1)			P <sub>D</sub>	321	W
Pulsed Drain Current (Note 2)	T <sub>C</sub> = 25°C		I <sub>DM</sub>	484	A
Single Pulse Surge Drain Current Capability	$\begin{array}{l} T_{A}=25^{\circ}C,t_{p}=10\;\mu s,\\ R_{G}=4.7\;\Omega \end{array}$		I <sub>DSC</sub>	798	A
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	–55 to +175	°C
Source Current (Body Diode)			۱ <sub>S</sub>	157	А
Single Pulse Drain-to-Source Avalanche Energy ( $I_{L(pk)} = 13 \text{ A}, L = 1 \text{ mH}$ ) (Note 3)			E <sub>AS</sub>	84	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)			ΤL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.

3. EAS of 84 mJ is based on starting  $T_J$  = 25°C; L = 1 mH,  $I_{AS}$  = 13 A,  $V_{DD}$  = 50 V,  $V_{GS}$  = 18 V.

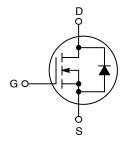


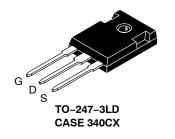
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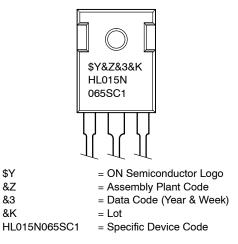
V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX	
650 V	18 mΩ @ 18 V	163 A	

# **N-CHANNEL MOSFET**





#### MARKING DIAGRAM



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 6 of this data sheet.

### THERMAL CHARACTERISTICS

Parameter	Symbol	Мах	Unit
Junction-to-Case - Steady State (Note 1)	$R_{\theta JC}$	0.24	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	40	

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA		650	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	$I_D = 20 \text{ mA}$ , referenced to $25^{\circ}\text{C}$		-	0.12	-	V/∘C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V,$ $T_{J} = 25^{\circ}C$		-	-	10	μA
		V <sub>DS</sub> = 650 V	T <sub>J</sub> = 175°C	-	-	1	mA
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = +22/-8$ V,	V <sub>DS</sub> = 0 V	-	-	250	nA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D =$	= 25 mA	1.8	2.63	4.3	V
Recommended Gate Voltage	V <sub>GOP</sub>			-5	-	+18	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 15 V, I <sub>D</sub> = 75	A, T <sub>J</sub> = 25°C	-	15	-	mΩ
		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 75	A, T <sub>J</sub> = 25°C	-	12	18	
		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 75 /	A, T <sub>J</sub> = 175°C	_	16	-	
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub>	= 75 A	_	44	-	S
CHARGES, CAPACITANCES & GATE RES	SISTANCE				1		
Input Capacitance	C <sub>ISS</sub>	$V_{\rm GS}$ = 0 V, f = 1 MHz, $V_{\rm DS}$ = 325 V		_	4790	-	pF
Output Capacitance	C <sub>OSS</sub>			_	430	-	
Reverse Transfer Capacitance	C <sub>RSS</sub>			_	33	-	
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = -5/18 \text{ V}, V_{DS} = 520 \text{ V},$ $I_D = 75 \text{ A}$		_	283	-	nC
Gate-to-Source Charge	Q <sub>GS</sub>			_	72	-	
Gate-to-Drain Charge	Q <sub>GD</sub>			-	64	-	
Gate-Resistance	R <sub>G</sub>	f = 1 MHz		_	1.6	-	Ω
SWITCHING CHARACTERISTICS							
Turn–On Delay Time	t <sub>d(ON)</sub>	V <sub>GS</sub> = -5/18 V,		-	23	-	ns
Rise Time	t <sub>r</sub>	V <sub>DS</sub> = 400 I <sub>D</sub> = 75 A		-	26	-	1
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$R_G = 2.2 \Omega$ inductive load		-	49	-	1
Fall Time	t <sub>f</sub>			_	9.6	-	
Turn–On Switching Loss	E <sub>ON</sub>			_	167	-	μJ
Turn-Off Switching Loss	E <sub>OFF</sub>			_	276	-	
Total Switching Loss	E <sub>tot</sub>			_	443	-	
SOURCE-DRAIN DIODE CHARACTERIST					1		
Continuous Source-Drain Diode Forward Current	I <sub>SD</sub>	$V_{GS}$ = -5 V, $T_{J}$ = 25°C		-	-	157	A
Pulsed Source-Drain Diode Forward	I <sub>SDM</sub>			_	_	484	

 $V_{GS}$  = –5 V,  $I_{SD}$  = 75 A,  $T_J$  = 25°C

4.6

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V

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 $\mathsf{V}_{\mathsf{SD}}$ 

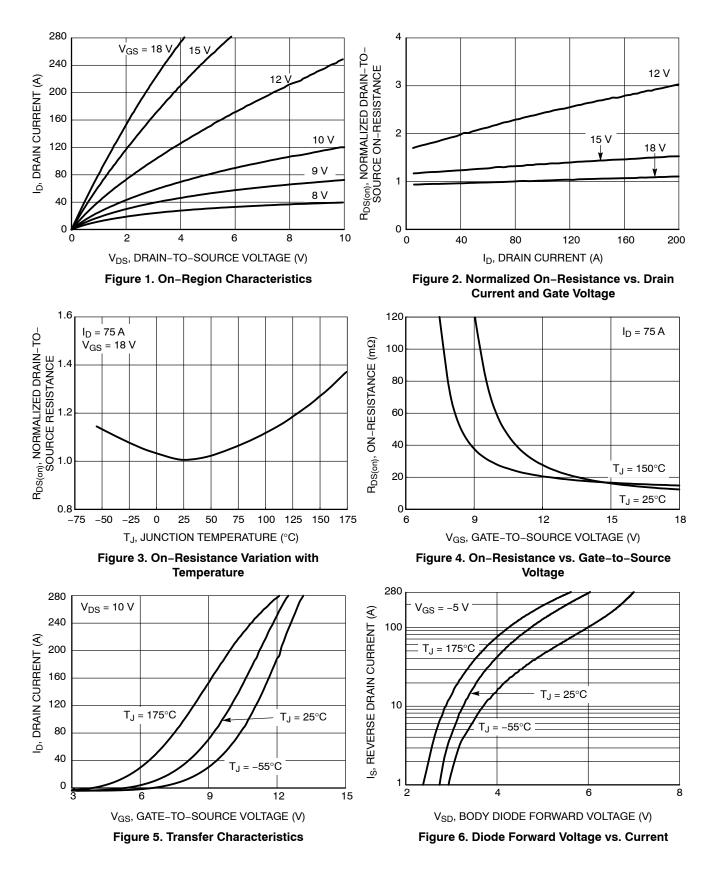
Forward Diode Voltage

# **ELECTRICAL CHARACTERISTICS** ( $T_J$ = 25°C unless otherwise specified) (continued)

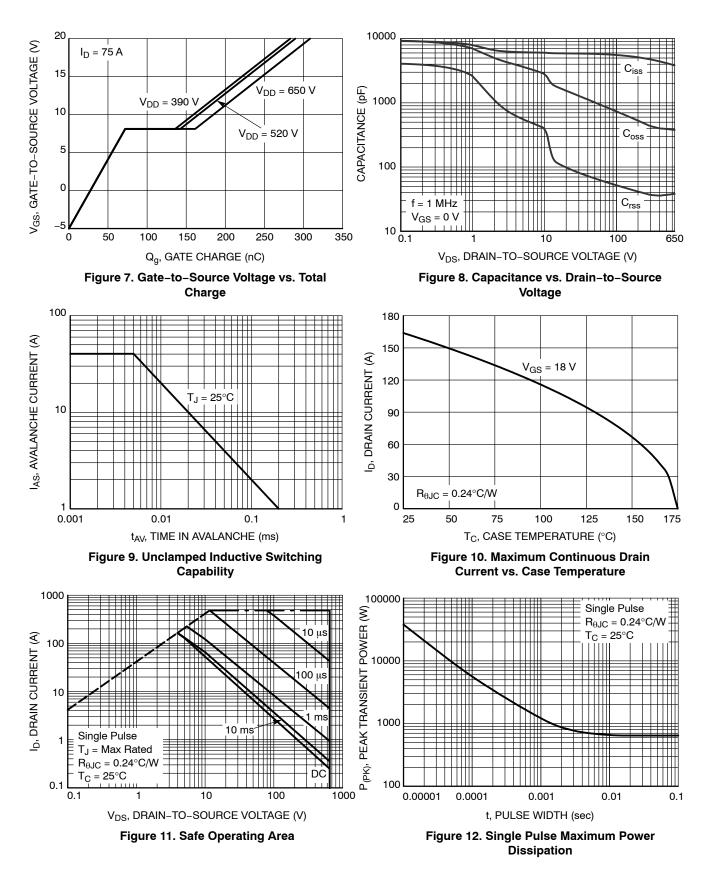
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit		
SOURCE-DRAIN DIODE CHARACTERI	SOURCE-DRAIN DIODE CHARACTERISTICS							
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = -5/18 V, I <sub>SD</sub> = 75 A, dI <sub>S</sub> /dt = 1000 A/μs	-	28	-	ns		
Reverse Recovery Charge	Q <sub>RR</sub>		-	234	-	nC		
Reverse Recovery Energy	E <sub>REC</sub>		-	23	-	μJ		
Peak Reverse Recovery Current	I <sub>RRM</sub>		-	16	-	А		
Charge time	Та		-	17	-	ns		
Discharge time	Tb		-	11	-	ns		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# **TYPICAL CHARACTERISTICS**



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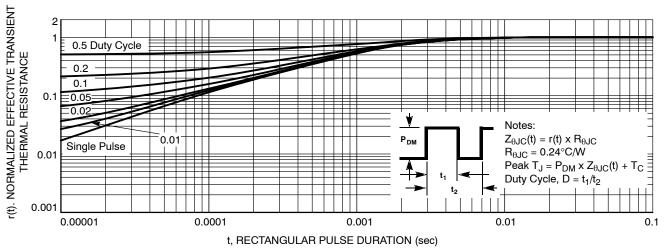
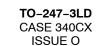


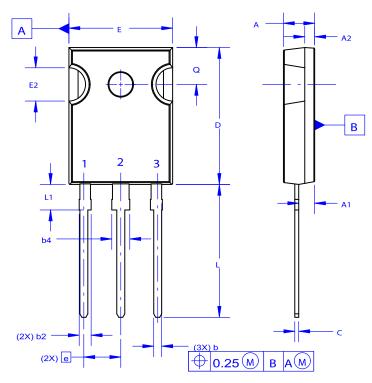
Figure 13. Junction-to-Case Thermal Response

## PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTHL015N065SC1	NTHL015N065SC1	TO-247 Long Lead	Tube	N/A	N/A	30 Units

### PACKAGE DIMENSIONS

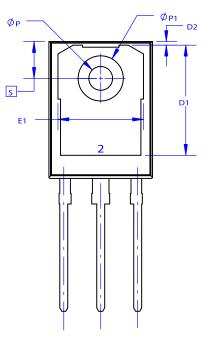




NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.

- D. DRAWING CONFORMS TO ASME Y14.5 2009.
  D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
  E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
E	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØР	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
Ø <b>P</b> 1	6.60	6.80	7.00		

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